				I m !
L	Hits	Search Text	DB	Time stamp
Number				0001/00/10
_	1	Transfer adj patterned adj metal adj cold-welding	USPAT; US-PGPUB; IBM TDB	2004/03/10 18:15
_	2	(("5294870") or ("4769292")).PN.	USPAT; US-PGPUB; IBM TDB	2004/03/10 18:18
_	1	("5925259").PN.	USPAT; US-PGPUB; IBM TDB	2004/03/10 18:19
_	7	("2897066" "3647508" "3716911" "4021279" "5512131" "5725788" "5772905").PN.	USPAT	2004/03/10 18:21
-	11	5925259.URPN.	USPAT	2004/03/10
-	5	("5641611" "5707745" "5925259" "6013538" "6027630").PN.	USPAT	2004/03/10 18:29
-	6	("5641611" "5707745" "5925259" "5998803" "6013538" "6027630").PN.	USPAT	2004/03/10 18:31
-	5247	(pattern\$3) and substrate and (thin adj film) and (press\$3) and die	USPAT; US-PGPUB; IBM TDB	2004/03/10 18:38
-	3316	(pattern\$3) same substrate and (thin adj film) and (press\$3) and die	USPAT; US-PGPUB; IBM TDB	2004/03/10 18:38
	990	(pattern\$3) same substrate same (thin adj film) and (press\$3) and die	USPAT; US-PGPUB; IBM TDB	2004/03/10 18:38
-	5	(pattern\$3) same substrate same (thin adj film) and (press\$3) and die and (cold adj weld\$3)	USPAT; US-PGPUB; IBM TDB	2004/03/10 18:41
_	194	<pre>(pattern\$3) same substrate same (thin adj film) same die and (press\$3)</pre>	USPAT; US-PGPUB; IBM TDB	2004/03/10 18:42
_	18	5259926.URPN.	USPAT	2004/03/10 18:47
-	9	("5641611" "5707745" "5925259" "5998803" "6013538" "6027630" "6190940" "6214631" "6504096").PN.	USPAT	2004/03/11 09:38
_	6	("5641611" "5707745" "5925259" "5998803" "6013538" "6027630").PN.	USPAT	2004/03/11 09:42
-	1	6468819.URPN.	USPAT	2004/03/11 09:42
-	5	("5641611" "5707745" "5925259" "6013538" "6027630").PN.	USPAT	2004/03/11
-	2	6294398.URPN.	USPAT	2004/03/11 09:43
-	434	<pre>(pattern\$3) same substrate same (electrode or (thin adj film)) same die and (press\$3)</pre>	USPAT; US-PGPUB; IBM TDB	2004/03/11 10:00
_	325	(pattern\$3) same substrate same (electrode or (thin adj film)) same die	USPAT; US-PGPUB;	2004/03/11 10:01
_	128	and (press\$3) and remov\$3 (pattern\$3) same substrate same (electrode or (thin adj film)) same die and (press\$3) and remov\$3 same die	IBM_TDB USPAT; US-PGPUB; IBM_TDB	2004/03/11 10:01
_	85	<pre>(pattern\$3) and remov\$3 same die (pattern\$3) same substrate same (electrode or (thin adj film)) same die and (press\$3 same die) and (remov\$3 same</pre>	USPAT; US-PGPUB; IBM_TDB	2004/03/11 10:43
_	20	die) 5900160.URPN.	USPAT	2004/03/11 10:12

_	35	("Re33581" "2905539" "3497377"	USPAT	2004/03/11
		"3641354" "3716359" "4011009"		10:23
		"4173075" "4274706" "4325779"		
		"4330175" "4382657" "4477158"		
		"4512848" "4528260" "4582566"		1
		"4587213" "4690715" "4728591"		
	1	"4731155" "4802951" "4818336"]
		"4842633" "4897325" "4999489"		
]	"5018829" "5020879" "5032216"		
		"5079600" "5143854" "5202227"		
		"5255273" "5259926" "5294369"	}	
		"5315436" "5512131").PN.		
_	1	("5512131").PN.	USPAT;	2004/03/11
	1	(US-PGPUB;	10:33
•			IBM TDB	
1_	37	(pattern\$3) same substrate same	USPAT;	2004/03/11
]	(electrode or (thin adj film)) same	US-PGPUB;	10:55
		stamp\$3 and (remov\$3 same stamp)	IBM TDB	10.00
	596	(die or stamp) and (cold adj weld\$3)	USPAT;	2004/03/11
-	396	(die of Stamp) and (cold ad) werdys)	US-PGPUB;	10:56
			IBM TDB	10.50
				2004/03/11
-	94	((die or stamp) same (cold adj weld\$3))	USPAT;	
		and substrate	US-PGPUB;	10:56
		() 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	IBM_TDB	2004/02/11
-	90	((die or stamp) same (cold adj weld\$3))	USPAT;	2004/03/11
		and substrate and (film or layer)	US-PGPUB;	10:57
			IBM_TDB	0004/00/27
-	64	((die or stamp) same (cold adj weld\$3))	USPAT;	2004/03/11
		and substrate and (film or layer) and	US-PGPUB;	10:57
		remov\$3	IBM_TDB	
_	50	((die or stamp) same (cold adj weld\$3))	USPAT;	2004/03/11
		and substrate and (film or layer) and	US-PGPUB;	10:58
		(remov\$3 same (die or stamp))	IBM_TDB	
_	228	(die or stamp) same (cold adj weld\$3)	USPAT;	2004/03/11
		•	US-PGPUB;	11:54
			IBM TDB	
_	6	("5772905" "5814885" "5925259"	USPAT	2004/03/11
		"6027630" "6274508" "6281038").PN.		11:27
_	35	("Re33581" "2905539" "3497377"	USPAT	2004/03/11
		"3641354" "3716359" "4011009"		11:48
		"4173075" "4274706" "4325779"		
		"4330175" "4382657" "4477158"		,
		"4512848" "4528260" "4582566"		
	,	"4587213" "4690715" "4728591"		
		"4731155" "4802951" "4818336"		
		"4842633" "4897325" "4999489"		
		"5018829" "5020879" "5032216"		
		"5079600" "5143854" "5202227"		
		"5255273" "5259926" "5294369"		
		"5315436" "5512131").PN.		
l _	598	(die or stamp or (forming adj member))	USPAT;	2004/03/11
1 -	396	and (cold adj weld\$3)	US-PGPUB;	11:55
		and (cord ad) werdys)	IBM TDB	
	229	(die or stamp or (forming adj member))	USPAT;	2004/03/11
-	229	and (cold adj weld\$3) and substrate	US-PGPUB;	11:55
		and (cord ad) werdys) and substrace	IBM TDB	
	7.0	(die an atomo on (farming add mamban))	USPAT;	2004/03/11
-	79		US-PGPUB;	11:58
		and (cold adj weld\$3) and substrate and	IBM TDB	11.50
		((metal or conduct\$3) adj (film or	T DII L DD	
	_	layer))	HCDATT.	2004/03/11
-	6		USPAT;	
1		with ((rais\$3 or project\$3 or protrud\$3)	US-PGPUB;	12:00
		adj portion)) and (cold adj weld\$3) and	IBM_TDB	
	1-	substrate and ((metal or conduct\$3) adj	1	
		(film or layer))	YIGD DE	2004/02/21
-	6		USPAT;	2004/03/11
		with ((rais\$3 or project\$3 or protrud\$3)	US-PGPUB;	12:03
1		adj portion)) and (cold adj weld\$3) and	IBM_TDB	
		substrate and ((metal or conduct\$3) adj		1
		(film or layer))		

	6	<pre>((die or stamp or (forming adj member)) with ((rais\$3 or project\$3 or protrud\$3) adj portion)) and (cold adj weld\$3) and</pre>	USPAT; US-PGPUB; IBM_TDB	2004/03/11 12:02
_	20	substrate ((die or stamp or (forming adj member)) with ((rais\$3 or project\$3 or protrud\$3) adj portion) or indentation) and (cold	USPAT; US-PGPUB; IBM_TDB	2004/03/11 12:02
_	1746	adj weld\$3) and substrate ((die or stamp or (forming adj member)) with ((rais\$3 or project\$3 or protrud\$3) adj portion) or indentation) and substrate and ((metal or conduct\$3) adj	USPAT; US-PGPUB; IBM_TDB	2004/03/11 12:04
_	711	<pre>(film or layer)) ((die or stamp or (forming adj member)) with ((rais\$3 or project\$3 or protrud\$3) adj portion) or indentation) and</pre>	USPAT; US-PGPUB; IBM_TDB	2004/03/11 12:04
-	99	substrate with ((metal or conduct\$3) adj (film or layer)) ((die or stamp or (forming adj member)) with ((rais\$3 or project\$3 or protrud\$3) adj portion) or indentation) and substrate with ((metal or conduct\$3) adj	USPAT; US-PGPUB; IBM_TDB	2004/03/11 12:06
_	9	<pre>(film or layer)) and ((press\$3 or forc@3) with (die or stamp or (forming adj member))) ((die or stamp or (forming adj member)) with ((rais\$3 or project\$3 or protrud\$3)</pre>	USPAT; US-PGPUB;	2004/03/11
		adj portion) or indentation) and substrate with ((metal or conduct\$3) adj (film or layer)) and ((press\$3 or forc@3) with (die or stamp or (forming adj member))) and ((releas\$3 or remov@3) with (die or stamp or (forming adj member)))	IBM_TDB	
_	1	("5707745").PN.	USPAT; US-PGPUB; IBM TDB	2004/03/11 16:26
-	130	heterostructure same polymer	USPAT; US-PGPUB; IBM TDB	2004/03/11 16:26
_	88	heterostructure with polymer	USPAT; US-PGPUB; IBM TDB	2004/03/11 16:26
-	5	heterostructure near polymer	USPAT; US-PGPUB; IBM TDB	2004/03/11 16:26
_	3	(forming adj member)) and (cold adj weld\$3) and substrate	USPAT; US-PGPUB; IBM_TDB	2004/03/11 17:55
-	4	(438/22,23).ccls. and (die or stamp or (forming adj member)) and (cold adj weld\$3) and substrate	USPAT; US-PGPUB; IBM_TDB	2004/03/11 17:55
_	1	(257/79,88).ccls. and (die or stamp or (forming adj member)) and (cold adj weld\$3) and substrate	USPAT; US-PGPUB; IBM_TDB	2004/03/11 17:56
_	112	((die or stamp or (forming adj member)) with ((rais\$3 or project\$3 or protrud\$3) adj portion)) and substrate and ((metal	USPAT; US-PGPUB; IBM_TDB	2004/03/11 17:57
_	61	or conduct\$3) adj (film or layer)) ((die or stamp or (forming adj member)) with ((rais\$3 or project\$3 or protrud\$3) adj portion)) and substrate and ((metal or conduct\$3) adj (film or layer)) and	USPAT; US-PGPUB; IBM_TDB	2004/03/11 17:59
		<pre>(die or stamp or (forming adj member)) with press\$3</pre>		

	23	((die or stamp or (forming adj member))	USPAT;	2004/03/11
	2.5	with ((rais\$3 or project\$3 or protrud\$3)	US-PGPUB;	18:00
			· ·	10.00
		adj portion)) and substrate and ((metal	IBM_TDB	
		or conduct\$3) adj (film or layer)) and		
		((die or stamp or (forming adj member))		
		with press\$3) and ((die or stamp or	:	
		(forming adj member)) with (remov\$3 or		
		releas\$3))		
	1	("6214631").PN.	USPAT;	2004/06/18
	-	(0221002 / 12110	US-PGPUB;	08:29
			IBM TDB	
	4.5	(houses man) a) in	USPAT;	2004/06/21
-	45	(burrows-paul-e).in.	· ·	09:32
i			US-PGPUB;	09:32
,			IBM_TDB	
-	25	(burrows-paul-e).in. and pattern\$3	USPAT;	2004/06/21
			US-PGPUB;	09:33
			IBM TDB	
	22	(burrows-paul-e).in. and pattern\$3 and	USPAT;	2004/06/21
	22	metal	US-PGPUB;	09:33
		mecar	IBM TDB	
	4	(house and softened and	_	2004/06/21
-	4	1 1 1	USPAT;	
		metal and die	US-PGPUB;	09:33
			IBM_TDB	